

MCD 0,5/ 4-G1-2,5 HT BK - PCB header



1961164

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PCB headers, nominal cross section: 0.5 mm^2 , color: black, nominal current: 4 A, rated voltage (III/2): 160 V, contact surface: Sn, contact connection type: Pin, number of potentials: 8, number of rows: 2, number of positions: 4, number of connections: 8, product range: MCD 0,5/..-G1-HT, pitch: 2.5 mm, mounting: THR soldering / wave soldering, pin layout: Linear pinning, solder pin [P]: 3.8 mm, number of solder pins per potential: 1, plug-in system: COMBICON FK-MC 0,5, Pin connector pattern alignment: Standard, locking: without, mounting method: without, type of packaging: packed in cardboard, Standard component made of highly temperature resistant plastic; suitable for reflow process. User information and design recommendations on Through Hole Reflow Technology can be found at: "Downloads".

Your advantages

- Designed for integration into the SMT soldering process
- Conductor connection on several levels enables higher contact density

Commercial data

Item number	1961164
Packing unit	50 pc
Minimum order quantity	50 pc
Sales key	AA01
Product key	AAATHA
GTIN	4017918912475
Weight per piece (including packing)	5.6 g
Weight per piece (excluding packing)	3.846 g
Customs tariff number	85366930
Country of origin	DE

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Technical data

Product properties

Product type	PCB headers
Product family	MCD 0,5/...-G1-HT
Product line	COMBICON Connectors XS
Type	Component suitable for through hole reflow
Number of positions	4
Pitch	2.5 mm
Number of connections	8
Number of rows	2
Number of potentials	8
Mounting type	without
Pin layout	Linear pinning
Solder pins per potential	1

Electrical properties

Properties

Nominal current I_N	4 A
Nominal voltage U_N	160 V
Contact resistance	3 mΩ
Rated voltage (III/3)	32 V
Rated surge voltage (III/3)	1.5 kV
Rated voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
Rated voltage (II/2)	160 V
Rated surge voltage (II/2)	2.5 kV

Mounting

Mounting type	THR soldering / wave soldering
Pin layout	Linear pinning

Processing notes

Process	Reflow/wave soldering
Moisture Sensitive Level	MSL 4
Classification temperature T_c	260 °C
Solder cycles in the reflow	3

Material specifications

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy

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Surface characteristics	Tin-plated
Metal surface contact area (top layer)	Tin (3 - 5 µm Sn)
Metal surface contact area (middle layer)	Nickel (1 - 3 µm Ni)
Metal surface soldering area (top layer)	Tin (3 - 5 µm Sn)
Metal surface soldering area (middle layer)	Nickel (1 - 3 µm Ni)

Material data - housing

Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	IIIa
CTI according to IEC 60112	325
Flammability rating according to UL 94	V0

Dimensions

Dimensional drawing	
Pitch	2.5 mm
Width [w]	11.9 mm
Height [h]	25.65 mm
Length [l]	17.5 mm
Installed height	21.85 mm
Solder pin length [P]	3.8 mm
Pin dimensions	0.8 x 0.8 mm

PCB design

Pin spacing	7.44 mm
Hole diameter	1.4 mm

Mechanical tests

Visual inspection

Specification	IEC 60512-1-1:2002-02
Result	Test passed

Dimension check

Specification	IEC 60512-1-2:2002-02
Result	Test passed

Resistance of inscriptions

Specification	IEC 60068-2-70:1995-12
Result	Test passed

Polarization and coding

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Specification	IEC 60512-13-5:2006-02
Result	Test passed

Contact holder in insert

Specification	IEC 60512-15-1:2008-05
Contact holder in insert Requirements >20 N	Test passed

Insertion and withdrawal forces

Result	Test passed
No. of cycles	25
Insertion strength per pos. approx.	7 N
Withdraw strength per pos. approx.	6 N

Electrical tests

Thermal test | Test group C

Specification	IEC 60512-5-1:2002-02
Tested number of positions	12

Insulation resistance

Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 5 MΩ

Air clearances and creepage distances |

Specification	IEC 60664-1:2007-04
Insulating material group	IIIa
Comparative tracking index (IEC 60112)	CTI 325
Rated insulation voltage (III/3)	32 V
Rated surge voltage (III/3)	1.5 kV
minimum clearance value - non-homogenous field (III/3)	0.8 mm
minimum creepage distance (III/3)	1.3 mm
Rated insulation voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
minimum clearance value - non-homogenous field (III/2)	1.5 mm
minimum creepage distance (III/2)	1.6 mm
Rated insulation voltage (II/2)	160 V
Rated surge voltage (II/2)	2.5 kV
minimum clearance value - non-homogenous field (II/2)	1.5 mm
minimum creepage distance (II/2)	1.6 mm

Environmental and real-life conditions

Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min

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Amplitude	0.35 mm (10 Hz ... 60.1 Hz)
Acceleration	5g (60.1 Hz ... 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis

Durability test

Specification	IEC 60512-9-1:2010-03
Impulse withstand voltage at sea level	2.95 kV
Contact resistance R ₁	3 mΩ
Contact resistance R ₂	3.2 mΩ
Insertion/withdrawal cycles	25
Insulation resistance, neighboring positions	> 5 MΩ

Climatic test

Specification	ISO 6988:1985-02
Corrosive stress	0.2 dm ³ SO ₂ on 300 dm ³ /40 °C/1 cycle
Thermal stress	100 °C/168 h
Power-frequency withstand voltage	1.39 kV

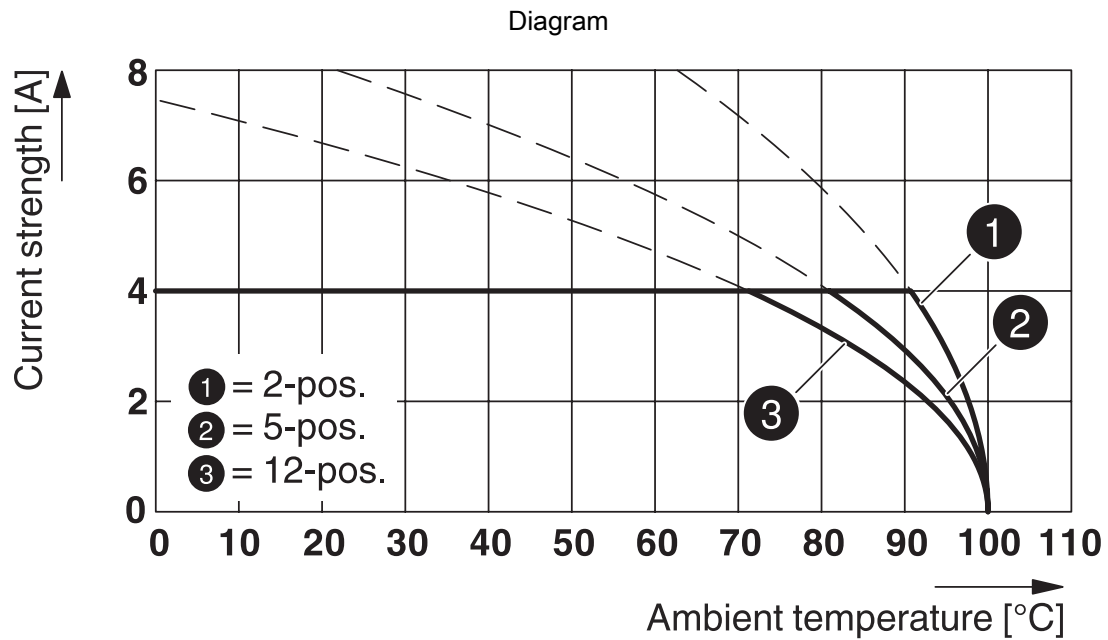
Ambient conditions

Ambient temperature (operation)	-40 °C ... 100 °C (dependent on the derating curve)
Ambient temperature (storage/transport)	-40 °C ... 70 °C
Relative humidity (storage/transport)	30 % ... 70 %
Ambient temperature (assembly)	-5 °C ... 100 °C

Packaging specifications

Type of packaging	packed in cardboard
Outer packaging type	Dry bag

Drawings



Type: FK-MC 0,5/...-ST-2,5 with MCD 0,5/...-G1-2,5 HT BK

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Classifications

ECLASS

ECLASS-13.0	27460201
ECLASS-15.0	27460201

ETIM

ETIM 9.0	EC002637
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UNSPSC

UNSPSC 21.0	39121400
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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions
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China RoHS

Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits

EU REACH SVHC

REACH candidate substance (CAS No.)	No substance above 0.1 wt%
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EF3.0 Climate Change

CO2e kg	0.095 kg CO2e
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